

WHAT IS CLAIMED IS:

1. An improved heat dissipating structure, comprising a heat dissipating member and a board member, wherein the board member includes an upper board and a lower board, and the upper board includes a plurality of recessed connecting structures formed on a top surface thereof,
5 the heat dissipating member includes a plurality of fins parallel to and spaced with each other to form a plurality of air circulating channels, each of the fins includes an embedding part along a bottom edge thereof engageable with the connecting structure to securely mount the heat dissipating structure
10 on the board member.
2. The heat dissipating structure according to Claim 1, wherein the upper board includes a hollow cuboid with an open bottom.
3. The heat dissipating structure according to Claim 1, wherein the lower board includes a hollow cuboid with an open top.
- 15 4. The heat dissipating structure according to Claim 1, wherein the upper board is made of aluminum or copper.
5. The heat dissipating structure according to Claim 1, wherein the lower board is made of aluminum or copper.
6. The heat dissipating structure according to Claim 1, wherein the
20 recessed connecting structures include dovetail slots.
7. The heat dissipating structure according to Claim 1, wherein the recessed connecting structures include rectangular slots.
8. The heat dissipating structure according to Claim 1, wherein the heat dissipating member includes an aluminum-extruded heat sink.
- 25 9. The heat dissipating structure according to Claim 1, wherein the heat dissipating member includes a stack-type heat sink.

10. The heat dissipating structure according to Claim 1, further comprising a fan mounted on the heat dissipating member.